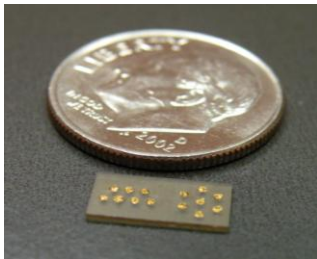


News Release

FOR IMMEDIATE RELEASE
8 A.M. MST, MAY 25, 2010
CONTACT: EDWARD PETSUCH



CUSTOM INTERCONNECTS THINNERPOSER®

DENVER, CO, MAY 25, 2010: **Custom Interconnects, LLC** announced the thinnest compliant board-to-board interposer ever developed: the Thinnerposer®. The Thinnerposer® was released to coincide with this week's IEEE IMS (International Microwave Symposium) and is expected to draw a great deal of interest from the RF design community. Targeted applications for the new Thinnerposer® technology include UAV/UAS, Avionics, Radar Arrays, Space Probes and Orbital Satellites.- a natural fit for the superior flexibility, impedance matching, and shock/vibration attributes of this product set.

“Our new Thinnerposer® lineup directly addresses the challenges of high density PCB stacking by supporting a mere .014” clearance between boards while ensuring high levels of signal integrity,” stated Edward Petsuch, General Manager of **Custom Interconnects**. “Thinnerposers® exploit the full potential of Fuzz Buttons®: low signal distortion, robustness and reliability. By combining our past 20 years of design experience and program successes with the power of this new product, we are well positioned to meet the demands of even the most stringent spec requirements.”

About **Custom Interconnects, LLC**:

Custom Interconnects (formerly named Tecknit Interconnection Products) is a technology-focused, quality-driven manufacturer of Board-to-Board Interposer, Test Socket and Interconnect solutions based upon unique Fuzz Button® technology. With footholds in several key industries including military, aerospace, RF/Microwave, semiconductor, medical electronics, and communications; the company is dedicated to performance, value and service.

More information about **Custom Interconnects** is available at
<http://www.custominterconnects.com>

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